















- ► Ceramic High Power
- ► 6868 1.85t Series
- ▶ Ultraviolet UVC (260-280nm)

N0Q58S08Z-260270 N0Q58S08Z-270280





6868 1.85t Series





FEATURES:

- Package: Ceramic SMT Package with Glass Lens
- Forward Current: 600mA Forward Voltage (typ.): 6V
- Radiant Power (typ.): 80mW@600mA
- Colour: Ultraviolet C (UVC) Peak Wavelength: 260~280nm
- Viewing angle: 120°
- **Materials:**
 - Die: AlGaN Flip Chip
 - Resin: Quartz Glass (Water Clear)
 - Electrodes: Au plated
- Operating Temperature: -30~+60°C Storage Temperature: -40~+100°C
- **Grouping parameters:**
 - Forward Voltage
 - **Radiant Power**
 - Peak Wavelength
- Soldering methods: IR Reflow
- Moisture Sensitive Level: MSL 2 according to J-STD020
- Packing: 12mm tape with min.100pcs/reel, ø180mm (7")

APPLICATIONS:

- Sterilization
- Air Purifier
- **Blood Detector**
- Skin Therapy
- Dermatology
- Water Purifier
- Disinfection







CHARACTERISTICS:

Absolute Maximum Characteristics (Ta=25°C)

Parameter	Symbol	Ratings	Unit
DC Forward Current	IF	800	mA
Power Dissipation	P _D	5.6	W
Junction Temperature	Tj	85	°C
Operating Temperature	T _{OPR}	-30~+60	°C
Storage Temperature	T _{STG}	-40~+100	°C

Electrical & Optical Characteristics (Ta=25°C)

Darameter	Symbol	Values			Unit	Test
Parameter	Зуппоп	Min.	Тур.	Max.	Offic	Condition
Forward Voltage	V _F	4.8	6.0	6.8	V	I _F =600mA
Radiant Power	Po	60	80	100	mW	I _F =600mA
Peak Wavelength	λD	260	270	280	nm	I _F =600mA
Viewing Angle	2θ _{1/2}		120		deg	I _F =600mA

^{1.} Radiant power (Φ_V) ±7%, Forward Voltage (V_F) ±0.05V, Viewing angle $(2\theta_{1/2})$ ±10°, Peak wavelength (λ_D) ±1nm.

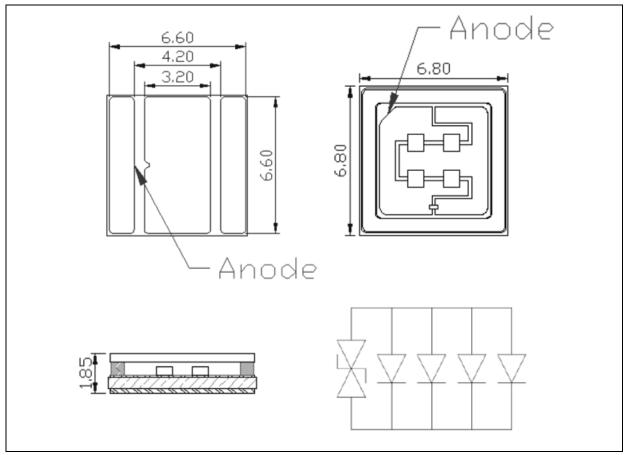






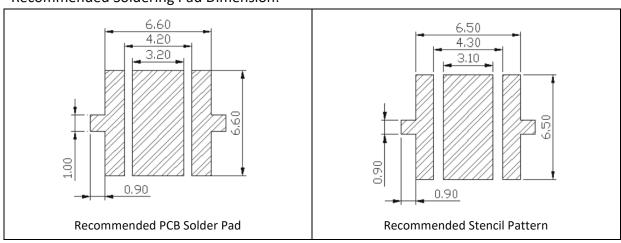
OUTLINE DIMENSION:

Package Dimension:



- 1. All dimensions are in millimetre (mm).
- 2. Tolerance ±0.13mm, unless otherwise noted.

Recommended Soldering Pad Dimension:



- 1. Dimensions are in millimetre (mm).
- 2. Tolerance ±0.12mm with angle tolerance ±0.5°.







BINNING GROUPS:

Forward Voltage Classifications (I_F = 600mA):

Code	Min.	Max.	Unit
JC	4.8	5.2	
JD	5.2	5.6	
JE	5.6	6.0	V
JF	6.0	6.4	
JG	6.4	6.8	

Radiant Power Classifications (I_F = 600mA):

Code	Min.	Max.	Unit
X07	50	65	
X08	65	80	mW
X09	80	100	

Peak Wavelength Classifications (I_F = 600mA):

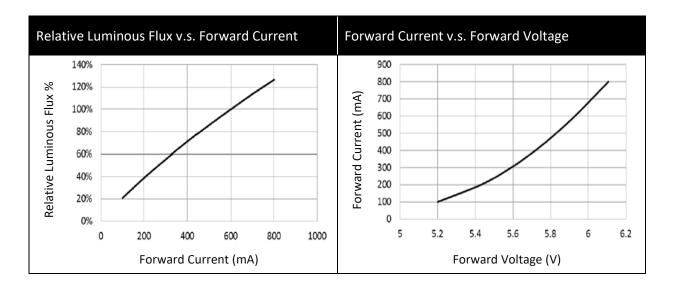
Code	Min.	Max.	Unit
265	260	270	2.22
275	270	280	nm

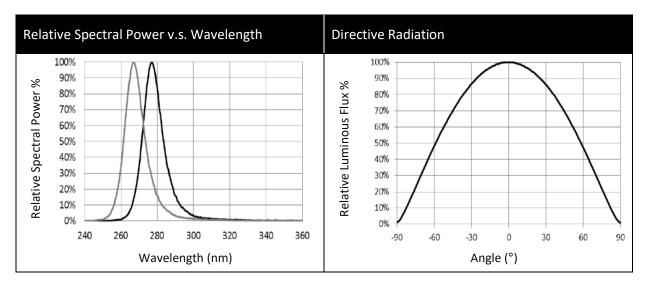






ELECTRO-OPTICAL CHARACTERISTICS:





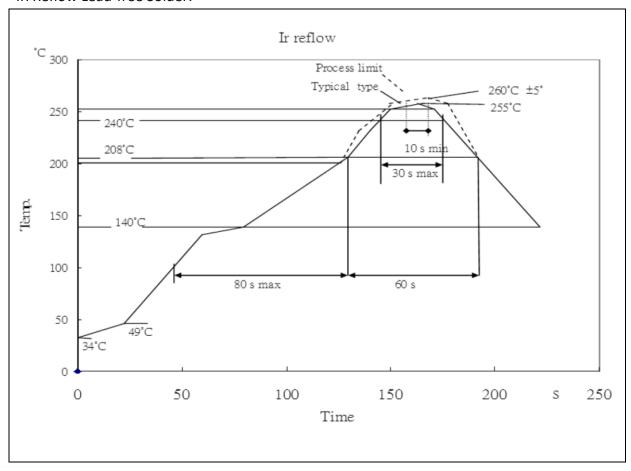






RECOMMENDED SOLDERING PROFILE:

IR Reflow Lead-free Solder:



Note:

- 1. Recommend reflow temperature 240°C. The maximum soldering temperature should be limited to 260°C.
- 2. Maxima reflow soldering: 1 time.
- 3. Before, during, and after soldering, should not apply stress on the components and PCB board.







PRECAUTIONS OF USE:

Storage:

It is recommended to store the products in the following conditions:

- Humidity: 60% R.H. Max.
- Temperature: 5°C~30°C (41°F ~86°F).

Shelf life in sealed bag: 12 months at 5°C~30°C and <60% R.H.

Once the package is opened, the products should be used within a week. Otherwise, they should be kept in a damp-proof box with descanting agent <10% R.H. and apply baking.

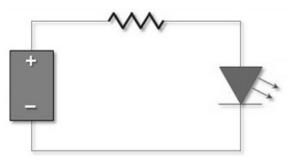
Baking:

It is recommended to bake the LED before soldering if the pack has been unsealed for longer than 24hrs. The suggested baking conditions are as followings:

60±3°C x 24hrs and <5%RH, taped / reel package.

It's normal to see slight color fading of carrier (light yellow) after baking in process.

Testing Circuit:



Must apply resistor(s) for protection (over current proof).

Cleaning:

Use alcohol-based cleaning solvents such as isopropyl alcohol to clean the LED carrier / package. Avoid putting any stress force directly on to the LED lens.

ESD (Electrostatic Discharge):

Static Electricity or power surge will damage the LED. Use of a conductive wrist band or anti-electrosatic glove is recommended when handing the LED all time. All devices, equipment, machinery, work tables, and storage racks must be properly grounded.

In the events of manual working in process, make sure the devices are well protected from ESD at any time.







REVISION RECORD:

Version	Date	Summary of Revision
A1.0	30/12/2020	Datasheet set-up.
A1.1	02/03/2021	Update bin table.